



Docket No.: 006301 USA/Consilium/Consilium

PATENT/OFFICIAL
2171

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re Application of

Badri N. KRISHNAMURTHY et al.

Serial No. 09/928,474

Filed: August 14, 2001

For: EXPERIMENT MANAGEMENT SYSTEM, METHOD AND MEDIUM

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Honorable Commissioner for Patents
Washington, D.C. 20231

Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

This submission does not constitute a representation that a search has been made or that no better art exists and does not constitute an admission or representation that any of the listed documents is material or constitutes prior art. If it should be determined that any of the listed documents does not constitute prior art under the United States law, Applicants reserve the right to present to the Office the relevant facts and law regarding the appropriate status of such document.

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Please charge the fee of \$180.00 under 37 CFR 1.17(p) to Deposit Account No. 08-0219.

The Commissioner is hereby authorized to charge any additional fees that may be required for this submission, or credit any overpayment to deposit account no. 08-0219.

Respectfully submitted,

HALE AND DORR LLP



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						Yes	No
	61-66104	04/04/86	Japan			X	
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	0 869 652	10/07/98	Europe			X	
	WO 99/09371	02/25/99	WIPO			X	
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	WO 00/00874	01/06/00	WIPO			X	
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	434103	05/16/01	Taiwan			X	
	436383	05/28/01	Taiwan			X	
	455938	09/21/01	Taiwan			X	
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	2001-284299	10/12/01	Japan			X	
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